



Material Content Data Sheet



Sales Product Name		IPT012N06N		Issued		19. January 2018		
MA#		MA001697810						
Package		PG-HSOF-8-1		Weight*		769.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.699	0.48	0.48	4804	4804
leadframe	inorganic material	phosphorus	7723-14-0	0.126	0.02		164	
	non noble metal	iron	7439-89-6	0.421	0.05		546	
	non noble metal	copper	7440-50-8	420.040	54.56	54.63	545553	546263
	non noble metal	aluminium	7429-90-5	12.784	1.66	1.66	16604	16604
wire	non noble metal	aluminium	7429-90-5	12.784	1.66	1.66	16604	16604
encapsulation	organic material	carbon black	1333-86-4	4.837	0.63		6283	
	plastics	epoxy resin	-	53.209	6.91		69109	
	inorganic material	silicondioxide	60676-86-0	264.434	34.34	41.88	343449	418841
leadfinish	non noble metal	tin	7440-31-5	6.479	0.84	0.84	8415	8415
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		2	
	non noble metal	nickel	7440-02-0	0.526	0.07	0.07	683	685
solder	non noble metal	tin	7440-31-5	0.068	0.01		88	
	noble metal	silver	7440-22-4	0.084	0.01		110	
	non noble metal	lead	7439-92-1	3.226	0.42	0.44	4190	4388
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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